

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims

Claim 1 (**Currently amended**): A socket system for coupling a pin of an IC (integrated circuit) device to a contact pad of a circuit board, comprising:

a zif (zero-insertion-force) opening on a socket that asserts substantially zero force as the pin of the IC device is inserted therein;

a compression mount lead disposed on the socket, wherein the compression mount lead includes a compression mechanism that compresses the compression mount lead that presses against the contact pad of the circuit board with a compressive force; and

~~a mechanism for coupling the pin to the compression mount lead using only a lateral direction of force on the pin during a process of coupling the pin to the compression mount lead.~~

Claim 2 (**Canceled**).

Claim 3 (**Currently amended**): The socket system of claim [[2]] 26, wherein the mechanism for coupling the pin to the compression mount lead comprises:

forking leads coupled to the compression mount lead and surrounding the pin within the zif opening; and

~~an actuation plate and an actuation lever that press the forking leads against the pin with force directed~~ the actuation plate being pressed toward the forking leads in only one lateral direction that is perpendicular to the length of the pin against the forking leads during the process of coupling such that the pin is coupled to the compression mount lead via the forking leads.

Claim 4 (**Previously presented**): The socket system of claim 3, wherein top portions of the forking leads contact a top portion of the pin toward the IC device to minimize an electrical path length between the IC device and the circuit board.

Claim 5 (**Currently amended**): The socket system of claim 1, wherein the compression mount ~~lead~~ mechanism is comprised of a pogo spring.

Claim 6 (**Currently amended**): The socket system of claim 1, wherein the compression mount lead is comprised of a J-bend lead ~~having a bottom surface that presses~~ is compressed against the contact pad of the circuit board.

Claim 7 (**Currently amended**): The socket system of claim 1, wherein the socket is mounted onto the circuit board such that the compression mount lead ~~presses~~ is compressed against the contact pad.

Claim 8 (**Previously presented**): The socket system of claim 1, wherein substantially zero force is asserted on the body of the IC device when the pin is coupled to the contact pad.

Claim 9 (**Previously presented**): The socket system of claim 1, further comprising:
a back plate mounted to a back-side of the circuit board when the socket is mounted to a front-side of the circuit board.

Claim 10 (**Previously presented**): The socket system of claim 1, wherein the socket and the circuit board are part of a test system for testing the IC device.

Claim 11 (**Previously presented**): The socket system of claim 1, wherein the socket and the circuit board are parts for an OEM (original equipment manufacturer) machine.

Claim 12 (**Currently amended**): A socket system for coupling a pin of an IC (integrated circuit) device to a contact pad of a circuit board, comprising:
means for asserting substantially zero force on the pin of the IC device as the pin is inserted into a zif (zero-insertion-force) opening on a socket; ~~and~~
means for compressing a compression mount lead against the contact pad of the circuit

board with a compressive force; and

means for coupling the pin of the IC device within the zif opening to the compression mount lead ~~contact pad of the circuit board using only a lateral direction of force on the pin during a process of coupling the pin to the contact pad.~~

Claim 13 (**Previously presented**): The socket system of claim 12, further comprising:
means for minimizing an electrical path length between the IC device and the circuit board.

Claim 14 (**Currently amended**): The socket system of claim 12, further comprising:
means for asserting substantially zero force on the body of the IC device when the pin is coupled to the ~~contact pad~~ compression mount lead with a force applied on the pin in a direction only perpendicular to a length of the pin.

Claim 15 (**Currently amended**): A method for coupling a pin of an IC (integrated circuit) device to a contact pad of a circuit board, including the steps of:
asserting substantially zero force on the pin as the pin of the IC device is inserted into a zif (zero-insertion-force) opening on a socket;
~~pressing~~ compressing a compression mount lead on the socket with a compressive force against the contact pad of the circuit board; and
coupling the pin to the compression mount lead ~~using only a lateral direction of force on the pin during a process of coupling the pin to the compression mount lead.~~

Claim 16 (**Canceled**).

Claim 17 (**Currently amended**): The method of claim [[16]] 27, further including the step of:
pressing forking leads against the pin with ~~force directed~~ an actuation plate that is pressed toward the forking leads in only one lateral direction that is perpendicular to the length of the pin ~~against the forking leads during the process of coupling within the zif opening such that the pin~~

is coupled to the compression mount lead via the forking leads.

Claim 18 (**Previously presented**): The method of claim 17, wherein top portions of the forking leads contact a top portion of the pin toward the IC device to minimize an electrical path length between the IC device and the circuit board.

Claim 19 (**Previously presented**): The method of claim 15, wherein the compression mount lead is comprised of a pogo spring.

Claim 20 (**Currently amended**): The method of claim 15, wherein the compression mount lead is comprised of a J-bend lead ~~having a bottom surface that presses~~ is compressed against the contact pad of the circuit board.

Claim 21 (**Currently amended**): The method of claim 15, further including the step of: mounting the socket onto the circuit board such that the compression mount lead ~~presses~~ is compressed against the contact pad.

Claim 22 (**Previously presented**): The method of claim 15, further including the step of: asserting substantially zero force on the body of the IC device when the pin is coupled to the contact pad.

Claim 23 (**Previously presented**): The method of claim 15, further including the step of: mounting a back plate to a back-side of the circuit board when the socket is mounted to a front-side of the circuit board.

Claim 24 (**Previously presented**): The method of claim 15, wherein the socket and the circuit board are part of a test system for testing the IC device.

Claim 25 (**Previously presented**): The method of claim 15, wherein the socket and the circuit board are parts for an OEM (original equipment manufacturer) machine.

Claim 26 (New): The socket system of claim 1, wherein the mechanism for coupling the pin to the compression mount lead applies a force on the pin in a direction that is always perpendicular to a length of the pin.

Claim 27 (New): The method of claim 15, further comprising:
coupling the pin to the compression mount lead with a force on the pin in a direction that is always perpendicular to a length of the pin.